信頼性試験成績書

0.18um Process Technology Product and Package

Legacy Fujitsu Reliability Engineering Test Report

Wafer Process : Aizu Fujitsu
Assembly : J-Devices

Reliability Test 1

Device Type : MCU 1
Package Type : Plastic LQFP-100 Package

Test Item	Test Condition	Tested Number		Tested Time	Failed Number
High Temperature Operation Life 高温連続動作試験	125 ℃ V_{DD}=Maximum Rating	231 (77x3Lots)		1000h	0
Power Temperature Cycling	-40℃～125℃	45	(a)	1000cyc	0
High Temperature Storage 高温保存試験	150 ℃	45		1000h	0
Temperature Cycling 温度サイクル	-65℃～150℃	231 (77x3Lots)	(a)	1000cyc	0
Unbiased HAST	130℃, 85%RH	231 (77x3Lots)	(a)	96h	0
HAST	110℃, 85%RH V_{DD}=Maximum Rating	231 (77x3Lots)	(a)	264h	0

(a) Pre-condition: Baking (125℃, 24h) +Moisture Absorption (30℃/60%RH, 192h) +IR 260℃ Max. x3

Endurance + Data Retention Test

Device Type : **MCU 2**
Package Type : **Plastic QFP-100 Package**

Test Condition (Ta)	Tested Number	Failed Number
10Kcyc (105℃) + Data Retention Bake : 1008h (150℃)	117 (3Lots)	0
10Kcyc (105℃) + HTOL : 1000h (150℃)	114 (3Lots)	0

Document History Page

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Rev.	ECN No.	Orig. of Change	Description of Change
**	5769784	KUMI	Initial release.